

DS90LV027

DS90LV027 LVDS Dual High Speed Differential Driver



Literature Number: SNLS003B

DS90LV027

LVDS Dual High Speed Differential Driver

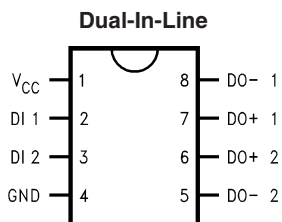
General Description

The DS90LV027 is a dual LVDS driver device optimized for high data rate and low power applications. The DS90LV027 is a current mode driver allowing power dissipation to remain low even at high frequency. In addition, the short circuit fault current is also minimized. The device is in a 8-lead small Outline Package. The DS90LV027 has a flow-through design for easy PCB layout. The differential driver outputs provides low EMI with its low output swings typically 340 mV. Perfect for high speed transfer of clock and data. Pair with any of National's LVDS receivers.

Features

- Ultra Low Power Dissipation
- Operating Range above 155 Mbps
- Flow-through pinout simplifies PCB layout
- Conforms to TIA/EIA-644 Standard
- 8-Lead SOIC Package Saves Space
- $V_{CM} \pm 1V$ center around 1.2V
- Low Differential Output Swing Typical 340 mV
- Power Off Protection (outputs in high impedance)

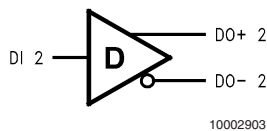
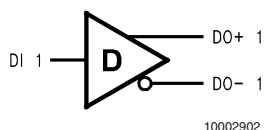
Connection Diagram



10002901

Order Number DS90LV027M
See NS Package Number M08A

Functional Diagram



Absolute Maximum Ratings (Note 1)

If Military/Aerospace specified devices are required, please contact the National Semiconductor Sales Office/Distributors for availability and specifications.

Supply Voltage (V_{CC})	-0.3V to +6V
Input Voltage (DI)	-0.3V to ($V_{CC} + 0.3V$)
Output Voltage (DO $\pm$)	-0.3V to +3.9V
Maximum Package Power Dissipation @ +25°C	
M Package	1190 mW
Derate M Package	9.5 mW/°C above +25°C
Storage Temperature Range	-65°C to +150°C

Lead Temperature Range

Soldering (4 sec.)

+260°C

ESD Rating (Note 4)

(HBM 1.5 k Ω , 100 pF)

≥ 4.5 kV

Recommended Operating Conditions

	Min	Typ	Max	Units
Supply Voltage (V_{CC})	3.0	3.3	3.6	V
Temperature (T_A)	0	25	70	°C

Electrical Characteristics

Over Supply Voltage and Operating Temperature ranges, unless otherwise specified. (Notes 2, 3, 7)

Symbol	Parameter	Conditions	Pin	Min	Typ	Max	Units
DIFFERENTIAL DRIVER CHARACTERISTICS							
V_{OD}	Output Differential Voltage	$R_L = 100\Omega$ (Figure 1)	DO+, DO-	250	340	450	mV
ΔV_{OD}	V_{OD} Magnitude Change			0	10	35	mV
V_{OH}	Output High Voltage				1.43	1.6	V
V_{OL}	Output Low Voltage			0.9	1.09		V
V_{OS}	Offset Voltage			0.9	1.25	1.6	V
ΔV_{OS}	Offset Magnitude Change			0	5	25	mV
I_{OZD}	TRI-STATE® Leakage	$V_{OUT} = V_{CC}$ or GND		0	± 1	± 10	μA
I_{OXD}	Power-off Leakage	$V_{OUT} = 3.6V$ or GND, $V_{CC} = 0V$		0	± 1	± 10	μA
I_{OSD}	Output Short Circuit Current				-4	-6	mA
V_{IH}	Input High Voltage	$V_{IN} = 3.6V$ or 2.4V	DI	2.0		V_{CC}	V
V_{IL}	Input Low Voltage			GND		0.8	V
I_{IH}	Input High Current				± 1	± 10	μA
I_{IL}	Input Low Current				± 1	± 10	μA
V_{CL}	Input Clamp Voltage	$I_{CL} = -18$ mA		-1.5	-0.8		V
I_{CC}	Power Supply Current	No Load	V_{CC}		1	4	mA
		$R_L = 100\Omega$			8	11	mA

Switching Characteristics

Over Supply Voltage and Operating Temperature Ranges, unless otherwise specified. (Notes 5, 6)

Symbol	Parameter	Conditions	Min	Typ	Max	Units
DIFFERENTIAL DRIVER CHARACTERISTICS						
t_{PHLD}	Differential Propagation Delay High to Low	$R_L = 100\Omega$, $C_L = 5$ pF (Figure 2 and Figure 3)	1.5	3.4	6	ns
t_{PLHD}	Differential Propagation Delay Low to High		1.5	3.5	6	ns
t_{SKD}	Differential Skew $ t_{PHLD} - t_{PLHD} $		0	0.1	1.9	ns
t_{TLH}	Transition Low to High Time		0	1	3	ns
t_{THL}	Transition High to Low Time		0	1	3	ns

Note 1: "Absolute Maximum Ratings" are those values beyond which the safety of the device cannot be guaranteed. They are not meant to imply that the devices should be operated at these limits. The table of "Electrical Characteristics" specifies conditions of device operation.

Note 2: Current into device pins is defined as positive. Current out of device pins is defined as negative. All voltages are referenced to ground except V_{OD} .

Note 3: All typicals are given for: $V_{CC} = +3.3V$ and $T_A = +25^\circ C$.

Note 4: ESD Rating: HBM (1.5 k Ω , 100 pF) ≥ 4.5 kV

Note 5: C_L includes probe and fixture capacitance.

Note 6: Generator waveform for all tests unless otherwise specified: $f = 1$ MHz, $Z_O = 50\Omega$, $t_r \leq 6$ ns, $t_f \leq 6$ ns (10%-90%).

Note 7: The DS90LV027 is a current mode device and only function with datasheet specification when a resistive load is applied to the drivers outputs.

Parameter Measurement Information

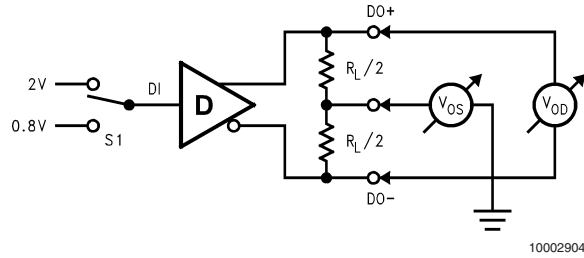


FIGURE 1. Differential Driver DC Test Circuit

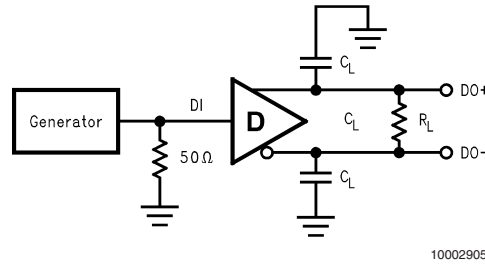


FIGURE 2. Differential Driver Propagation Delay and Transition Time Test Circuit

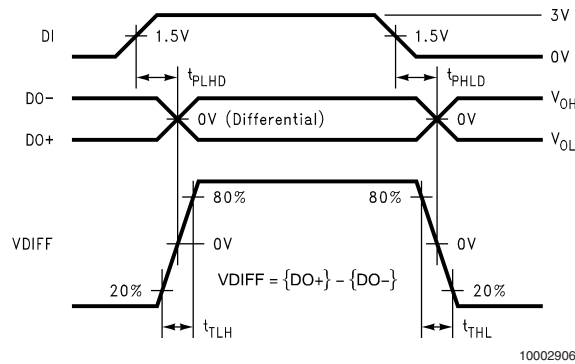


FIGURE 3. Differential Driver Propagation Delay and Transition Time Waveforms

Application Information

Truth Table

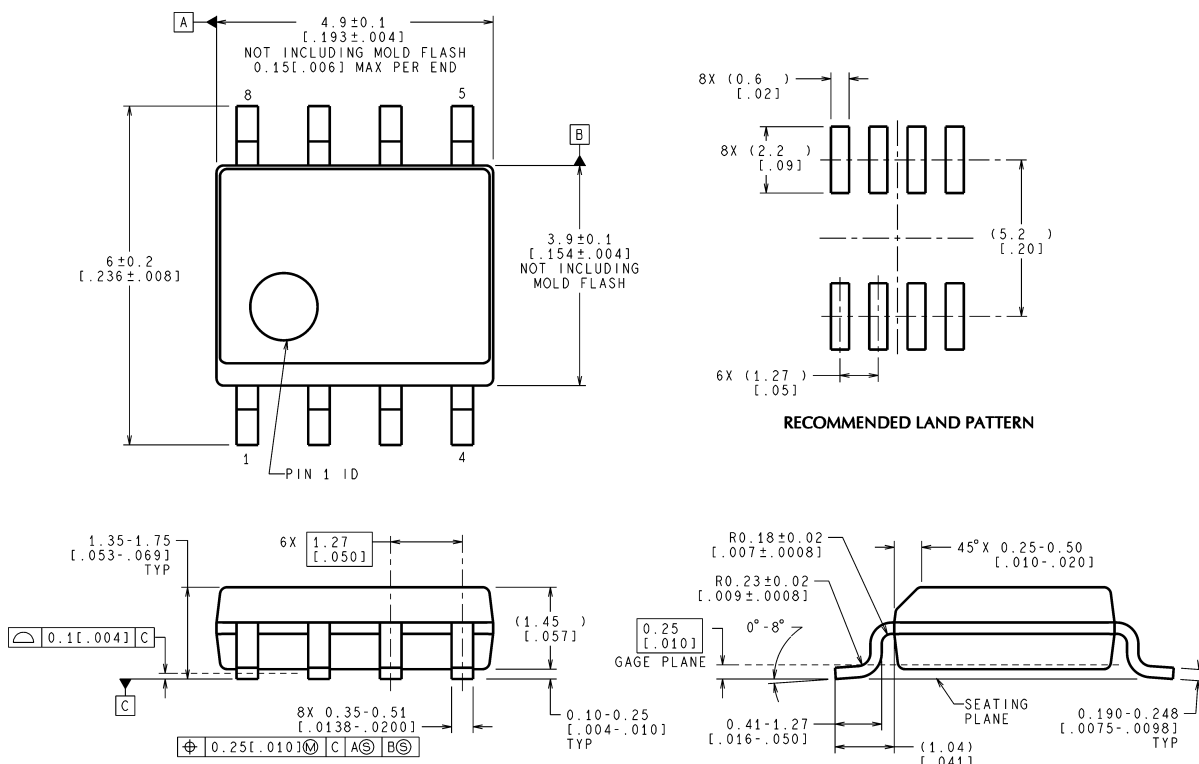
Input/Output		
DI	DO+	DO-
L	L	H
H	H	L
DI > 0.8V and DI < 2.0V	X	X

H = Logic high level
L = Logic low level
X = indeterminant

TABLE 1. Device Pin Descriptions

Pin #	Name	Description
2, 3	DI	TTL/CMOS driver input pins
6, 7	DO+	Non-inverting driver output pin
5, 8	DO-	Inverting driver output pin
4	GND	Ground pin
1	V _{CC}	Positive power supply pin, +3.3V ± 0.3V

Physical Dimensions inches (millimeters) unless otherwise noted



CONTROLLING DIMENSION IS MILLIMETER
VALUES IN [] ARE INCHES
DIMENSIONS IN () FOR REFERENCE ONLY

M08A (Rev K)

Order Number DS90LV027M
NS Package Number M08A

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